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Appl. No. : 10/799,905
Applicant : Thomas J. O'Keefe, et al.
Filed : March 12, 2004
Title : PROCESS FOR SPONTANEOUS DEPOSITION FROM AN
: ORGANIC SOLUTION
TC/A.U. : 1795
Examiner : William T. Leader
Docket No. : 31550-1001

United States Patent Application
DECLARATION

As a below named inventor I hereby declare under penalty of perjury under the laws of the United States of America that the following is true and correct:

1. "The document "Pd-Cu Co-deposition on TiSiN as seeds for electroless plating," by Jingye Li was only available to members of my research team in closed meetings within the confines of the research laboratory at the University of Missouri.
2. The document is merely a work summary prepared as an internal quarterly report to me.
3. The document was never made available to the public, and therefore was never published."

Signature:


Matthew O'Keefe

Executed on Date: May 19, 2009